

MATERIAL DECLARATION SHEET



Material Number	ESD Suppressing Device CDDFN2-T5.0LC			
Product Line	Semiconductor Products			
Compliance Date	2013/8/2			
RoHS Compliant	Yes	MSL	3	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Wafer	Silicon	0.05	Silicon	7440-21-3	100.00%	4.501%	4.501%
2	Lead frame	Copper Alloy (NiPdAu)	0.4182	Copper	7440-50-8	95.31%	37.649%	39.503%
			0.013	Nickel	7440-02-0	2.97%	1.170%	
			0.0028	Silicon	7440-21-3	0.64%	0.252%	
			0.0007	Magnesium	7439-95-4	0.15%	0.063%	
		Ni plating	0.0037	Nickel	7440-02-0	0.85%	0.333%	
		Pd plating	0.0003	Palladium	7440-57-3	0.06%	0.027%	
		Au plating	0.0001	Gold	7440-57-5	0.02%	0.009%	
3	Epoxy	Polymer	0.0255	Aluminum oxide	1344-28-1	50.00%	2.296%	4.591%
			0.006	Epoxy resin	Proprietary	11.7%	0.537%	
			0.017	Epoxy resin	Proprietary	33.3%	1.529%	
			0.0025	Aromatic amine	Proprietary	5.00%	0.229%	
4	wire	Noble metal	0.0099	Gold	7440-57-5	99.99%	0.891%	0.9%
			0.0001	Misc, not to declare	/	0.01%	0.009%	
			0.525	Silica Fused	60676-86-0	93.70%	47.265%	

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			0.017	Epoxy Resin	Proprietary	3.00%	1.530%	
			0.017	Phenol Resin	Proprietary	3.00%	1.530%	
			0.002	Carbon Black	1333-86-4	0.30%	0.180%	
		Total weight	1.1108 mg					

This Document was updated on: 2015/01/13

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.